CLAIMS

What is claimed is:

~~1. Apparatus for removing at least one chip-type semiconductor component from an adhesive film having first and second main surfaces, wherein the chip-type semiconductor component is arranged on the first main surface of the adhesive film, the apparatus comprising:~~

~~a removal device for removing the semiconductor component from the adhesive film, said removal device including~~

~~a lifting device configured to be arranged at the second main surface of the adhesive film, wherein said lifting device has a contact region for arrangement with respect to the adhesive film, said contact region having a plurality of first, suction, cutouts and second cutouts configured to receive pin-type lifting means;~~

~~said lifting device further including a Peltier element for changing the temperature of the adhesive film;~~

~~wherein at least some of said suction cutouts are connected to a vacuum regulating device.~~

2. The apparatus of claim **1**, wherein said contact region of said lifting device is configured to allow the passage therethrough of an end which is one of pointed and convex of one of the pin-type lifting means.

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CLAIMS

What is claimed is:

1. Apparatus for removing at least one chip-type semiconductor component from an adhesive film, wherein the semiconductor component is arranged on a first main surface of the film, having a removal apparatus for the semiconductor component and having a lifting apparatus that can be arranged on a second main surface of the film, wherein the said lifting apparatus has a contact region for arrangement on the film, which for its part has a plurality of suction cut-outs and cut-outs for pin-shaped lifting means, wherein all the suction cut-outs are connected in common to one vacuum regulation apparatus, or at least two suction cut-outs or groups of suction cut-outs are connected to separate vacuum regulation apparatuses, characterised in that the vacuum regulation apparatus or the separate vacuum regulation apparatuses are designed in such a manner that a defined vacuum is applied to the film and is kept constant or adjusted over time.

2. The apparatus of claim 1, wherein said contact region of said lifting device is configured to allow the passage there-through of an end which is one of pointed and convex of one of the pin-type lifting means.